



SOT176-1

plastic small outline package; 8 leads; body width 7.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO8
Package type industry code	SO8
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

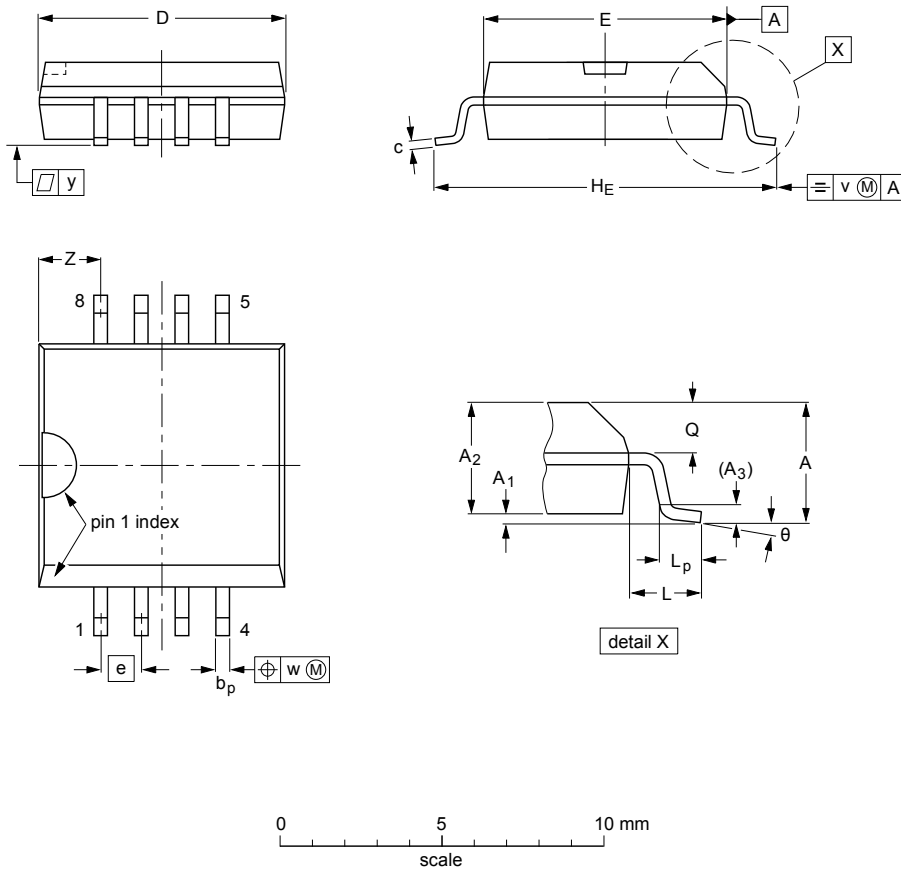
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.45	-	7.55	7.65	mm
E	package width	7.4	-	7.5	7.6	mm
A	seated height	[tbd]	-	2.65	2.65	mm
A ₂	package height	2.25	-	2.35	2.45	mm
n ₂	actual quantity of termination	-	-	8	-	



2. Package outline

SO8: plastic small outline package; 8 leads; body width 7.5 mm

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	7.65 7.45	7.6 7.4	1.27	10.65 10.00	1.45	1.1 0.45	1.1 1.0	0.25	0.25	0.1	2.0 1.8	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.30 0.29	0.30 0.29	0.05	0.419 0.394	0.057	0.043 0.018	0.043 0.039	0.01	0.01	0.004	0.079 0.071	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT176-1					-97-05-22 03-02-19

Fig. 1. Package outline SO8 (SOT176-1)

3. Soldering

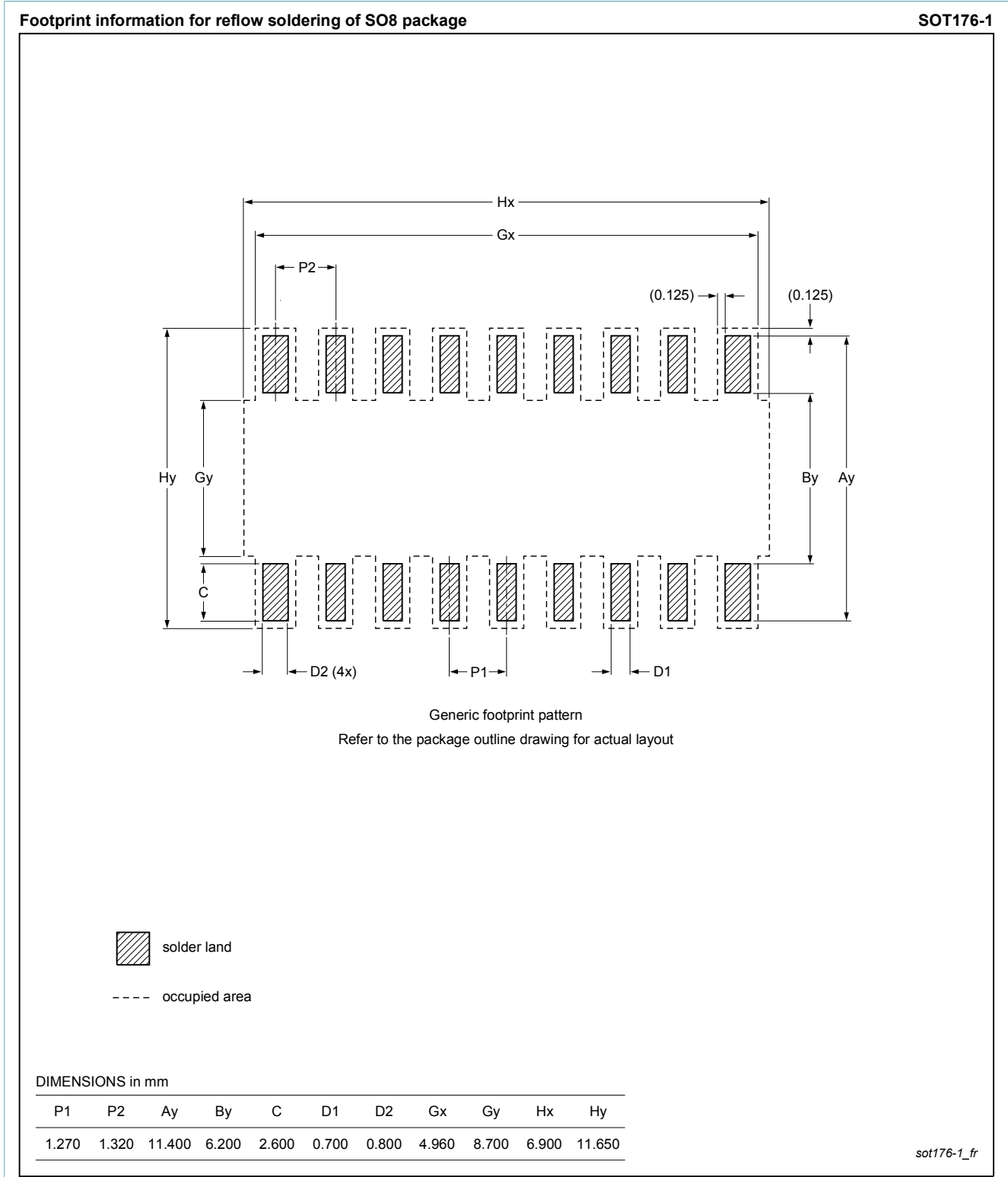
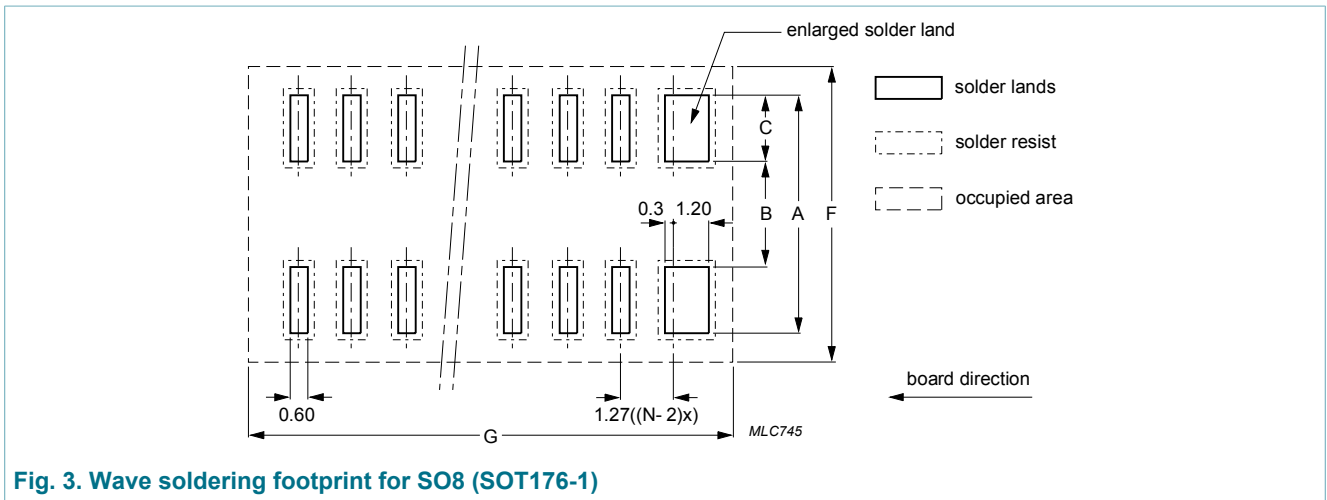


Fig. 2. Reflow soldering footprint for SO8 (SOT176-1)

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4. Legal information

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